# **Electronic Polymers**

# Honeywell



Honeywell ACCUSPIN<sup>®</sup> Boron Spin-on Dopant

## Honeywell **ACCUSPIN® Boron Spin-on** Dopant

## POLYMERS FOR ALL P-TYPE DIFFUSION

## BENEFITS

- Industry proven performance in analog CMOS, power, discrete and bipolar devices
- · Lower maintenance cost than gas or liquid sources
- Lower cost of ownership than source wafer doping or outsourced ion implanting
- Better control of sheet resistance non-uniformity to within 1% within a wafer and 2% wafer to wafer

## **OVERVIEW**

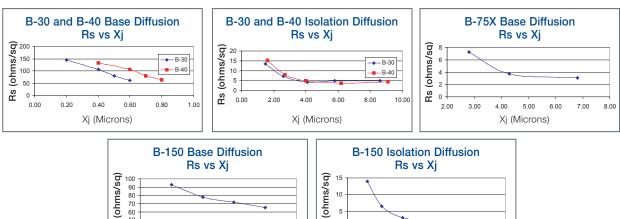
The ACCUSPIN B-XXX Spin-on dopant series are borosilicate (B-30, B-40, B-60) and boron nitrogen (B-75X, B-150) polymers designed for p-type base, isolation, p-type emitter diffusion, diode and deep p junction diffusion. The B-XXX series has been in large volume IC production for over 25 years. B-XXX can be applied using standard spin coaters.

ACCUSPIN B-XXX materials provide a lower cost of ownership than other dopant sources and reduce the need for costly diffusion furnace tube cleaning or replacement, required when using gas or liquid boron dopants.

Because the B-XXX materials are Spin-on borosilicates or boron nitrogen, diffusion is more uniform during the drive-in process so sheet resistance and junction depths are repeatable. The use of a Spin-on process eliminates non-uniformity issues due to changes in gas flows of boron sources and differing boron sheet resistance from placement in the diffusion furnace.

A Spin-on process also increases diffusion furnace throughput because every wafer boat slot can be used for production wafers.

### Sheet Resistance vs Junction Depth



10 5

> 0 0.00 2.00

4.00 6.00 8.00

Xj (Microns)

ß

0.80



#### **Honeywell Electronic Materials**

40

0.30

0 4 0

0.50

Xj (Microns)

0.60

å

USA: 1-509-252-2102 China: 86-21-28942481 Germany: 49-5137-999-9199 Japan: 81-3-6730-7092 Korea: 82-2-3483-5076 Singapore: 65-6580-3593 Taiwan: 886-3-6580300 ext.312 www.honeywell.com/sm/em

Although all statements and information contained herein are believed to be Attrough all statements and information contained nerein are believed to be accurate and reliable, they are presented without guarantee or warranty of any kind, express or implied. Information provided herein does not relieve the user from the responsibility of carrying out its own tests and experiments, and the user assumes all risks and liability for use of the information and results obtained. Statements or suggestions concerning the use of materials and pro-cesses are made without representation or warranty that any such use is free of patent information and are not recommendations to informe any patent. The user should not assume that all toxicity data and safety measures are indice user should not assume that all toxicity data and safety measures are indice PB0791011Rev10 patent infringement and are not recommendations to infringe any patent. The re indicated ©2011 Honevwell International Inc

0.70

### **APPLICATIONS**

- Bipolar
- Analog CMOS
- Discretes
- Power

ACCUSPIN B-XXX materials provide excellent sheet resistance non-uniformity within the wafer (1%) and from wafer to wafer (2%). The B-XXX series has been used in analog CMOS, power, discrete and bipolar device production around the world.

## **FEATURES**

### Thickness

Product	Thickness Range
B-30	4,100Å – 5,100Å
B-40	5,170Å – 5,570Å
B-60	4,400Å – 4,950Å
B-75X	2,900Å – 3,600Å
B-150	4,500Å – 5,100Å

#### Material Properties

B-30 Shelf Life @ 0-4°C: 6 months B-40 Shelf Life @ 0-4°C: 4 months B-60 Shelf Life @ 0-4°C: 3 months B-75X Shelf Life @ 20°C:\* 6 months B-150 Shelf Life @ 20°C:\* 12 months \*Room Temperature

Bottle Sizes Available 125ml, 250ml, 500ml, 1L, 2L, 4L



10.00 12.00